

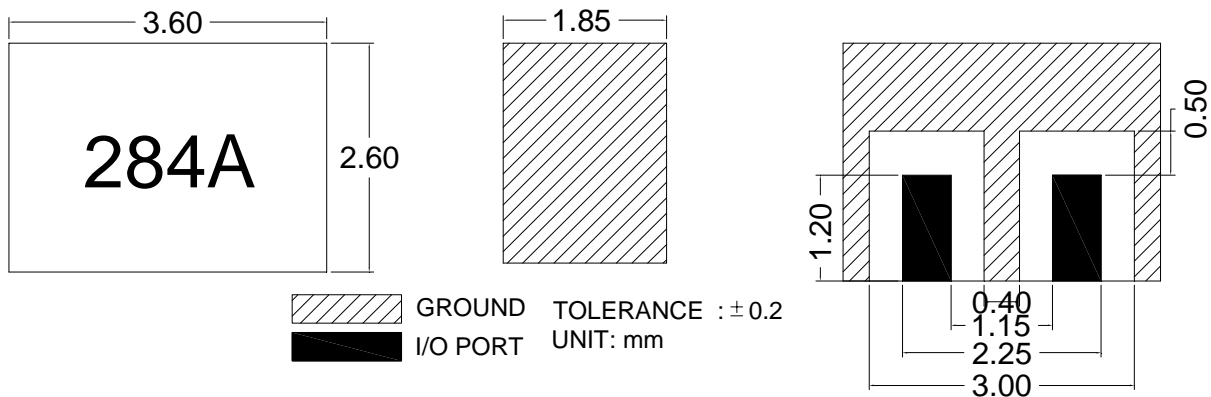
FEATURES

- Small Size,Light weight
- SMT package soldering
- Ideal for Microwave telecommunication

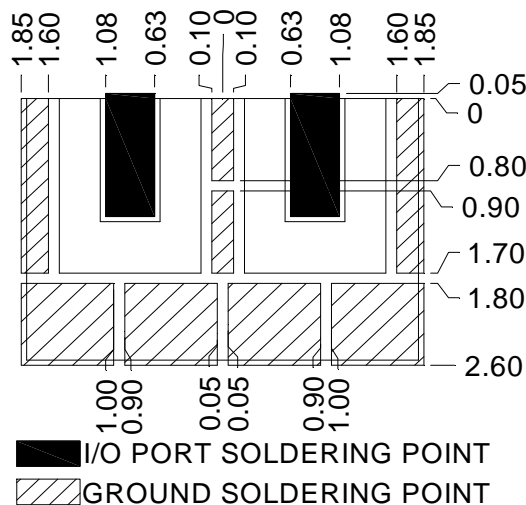
SPECIFICATIONS

| NO. | ITEM | SPEC | UNIT |
|-----|-----------------------|--|------|
| 1 | Center Frequency [fo] | 5665.0 | MHz |
| 2 | Bandwidth [BW] | fo±185 | MHz |
| 3 | Insertion Loss in BW | 3.0max | dB |
| 4 | Ripple in BW | 1.0 max | dB |
| 5 | VSWR in BW | 1.9:1max | / |
| 6 | Attenuations | 30.0 min @ 2400 ~2500 MHz 25.0 min @ 5150~ 5340 MHz | dB |

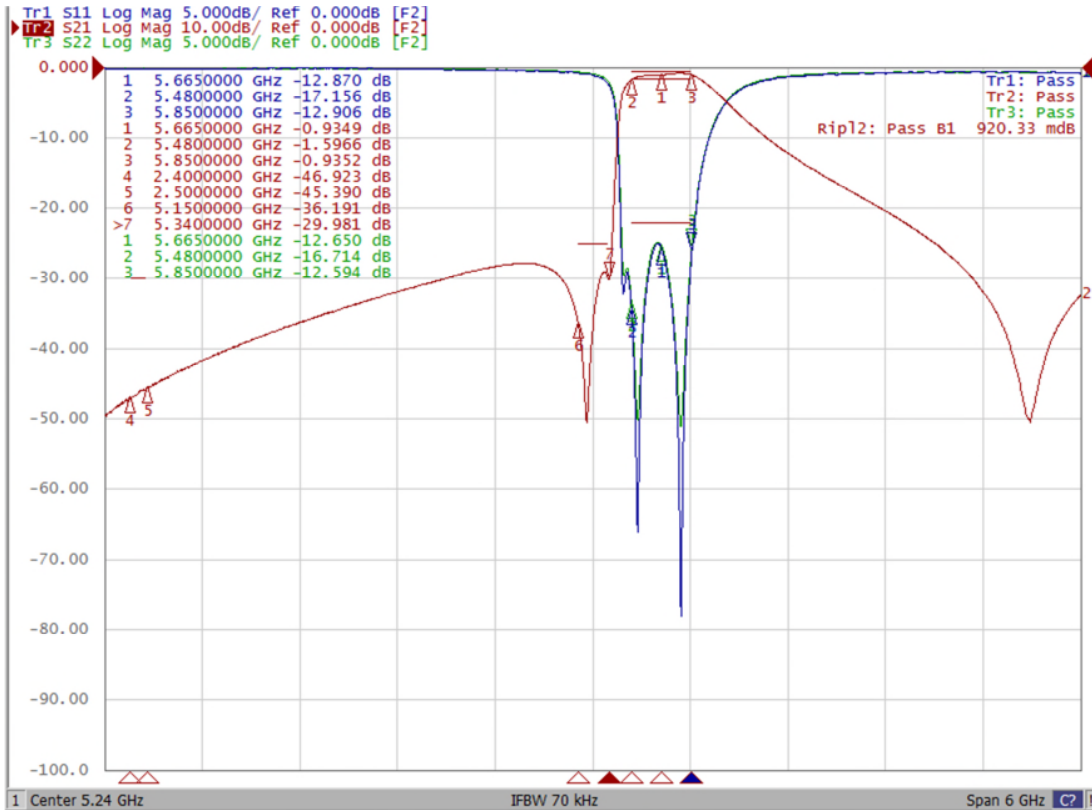
OUTLINE DRAWING



FOOTPRINT



ELECTRICAL CHARACTERISTICS CURVE



ABSOLUTE MAXIMUM RATINGS

| | |
|------------------------------|----------------|
| Operation Temperature | -40°C to +85°C |
| Storage Temperature | -40°C to +85°C |
| Input Power | 1 w max |

NOTES

- RoHS 2.0/HSF
- Reflow soldering temperature curve

